

CITATION REPORT

List of articles citing

Manipulating Crystallographic Texture of Sn Coatings by Optimization of Electrodeposition Process Conditions to Suppress Growth of Whiskers

DOI: 10.1007/s11664-014-3622-3

Journal of Electronic Materials, 2015, 44, 1206-1219.

Source: <https://exaly.com/paper-pdf/62217073/citation-report.pdf>

Version: 2024-04-09

This report has been generated based on the citations recorded by exaly.com for the above article. For the latest version of this publication list, visit the link given above.

The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

| # | Paper | IF | Citations |
|----|---|-----|-----------|
| 18 | Macro and micro-texture study for understanding whisker growth in Sn coatings. 2016 , | | 1 |
| 17 | Electromigration in Metallic Materials and Its Role in Whiskering. 2017 , 173-206 | | 1 |
| 16 | Identification of whisker grain in Sn coatings by analyzing crystallographic micro-texture using electron back-scatter diffraction. <i>Acta Materialia</i> , 2017 , 134, 346-359 | 8.4 | 29 |
| 15 | Effect of Substrate Composition on Whisker Growth in Sn Coatings. <i>Journal of Electronic Materials</i> , 2018 , 47, 4177-4189 | 1.9 | 7 |
| 14 | Sn Whiskers Nucleation and Growth - Short Review. <i>Solid State Phenomena</i> , 2018 , 280, 175-180 | 0.4 | 1 |
| 13 | Alkoxylated ENaphthol as an Additive for Tin Plating from Chloride and Methane Sulfonic Acid Electrolytes. <i>Coatings</i> , 2018 , 8, 79 | 2.9 | 3 |
| 12 | Critical Evaluation of Relative Importance of Stress and Stress Gradient in Whisker Growth in Sn Coatings. <i>Journal of Electronic Materials</i> , 2018 , 47, 5229-5242 | 1.9 | 9 |
| 11 | Morphology, resistivity and corrosion behavior of tin coatings plated from citric acid bath. <i>Materials Research Express</i> , 2019 , 6, 116589 | 1.7 | 2 |
| 10 | Whisker growth under a controlled driving force: Pressure induced whisker nucleation and growth. <i>Scripta Materialia</i> , 2020 , 182, 43-47 | 5.6 | 11 |
| 9 | Whisker Growth in Sn Coatings: A Review of Current Status and Future Prospects. <i>Journal of Electronic Materials</i> , 2021 , 50, 735-766 | 1.9 | 5 |
| 8 | Temperature driven texture and grain boundary engineering of electrodeposited EN coatings and its effect on the coating corrosion behaviour: Five-parameter grain boundary character distribution analysis study. <i>Scripta Materialia</i> , 2021 , 196, 113763 | 5.6 | 2 |
| 7 | Texture and grain boundary engineering in electrodeposited SnCu coatings and its effect on coating corrosion behaviour. <i>Philosophical Magazine</i> , 2021 , 101, 2036-2053 | 1.6 | 0 |
| 6 | Tuning the electrodeposition texture of EN coatings for enhanced corrosion resistance. <i>Microscopy and Microanalysis</i> , 2021 , 27, 722-724 | 0.5 | |
| 5 | Understanding Whisker Growth: Effect of Substrate and Underlayer. <i>International Symposium on Microelectronics</i> , 2016 , 2016, 000512-000515 | 0.2 | 1 |
| 4 | Electrodeposition current density induced texture and grain boundary engineering in Sn coatings for enhanced corrosion resistance. <i>Corrosion Science</i> , 2022 , 194, 109945 | 6.8 | 3 |
| 3 | Effect of Deposition Temperature on the Evolution of Texture, Grain Boundary Constitution and Corrosion Behaviour of SnCu Coatings. 2022 , 53, 3795-3806 | | 0 |
| 2 | Micromorphology and texture of niobium coating electrodeposited in NaCl/KCl/NaCl molten salt system. 2022 , 32, 3650-3662 | | 0 |

1

Sn Whisker Growth During Mechanical Loading and Unloading: Highlighting the Critical Role of Stress in Whisker Growth.

o